

ABSTRACT

The present invention provides a novel system, apparatus, and method to deposit conductive films on a workpiece. A system for electroplating a surface of a workpiece using a process solution is disclosed. The system comprises a solution housing configured to house an electrode and to contain the process solution, a filter element disposed in the solution housing configured to partition the solution housing into a lower chamber and an upper chamber, and an upper inlet port coupled to the solution housing configured to deliver the process solution to the upper chamber of the solution housing to fill the upper chamber and the lower chamber immersing the electrode in the lower chamber.